

A full-day Short Course on Introduction to Flip Chip Assembly to IEEE EPS Student Chapter of Nottingham University Malaysia

9th Mar 2024



- **With the main purpose of building Semiconductor Packaging Talent Pool in Malaysia, IEEE EPS Malaysia took an initiative to provide exposure about IC packaging specifically on Flip Chip assembly to engineering students from IEEE Student Chapter of Nottingham University Malaysia. A one-day short course was designed to suit at least 2nd year students in introduction of semiconductor packaging.**
- **Total of 26 students attended the short course, with lunch sponsored by IEEE EPS Malaysia.** Besides the topic, students were also introduced to working environment in semiconductor packaging such as clean room environment, smock (attire), and roles & responsibility of process engineers. At the end of the course, students were given questions to test their understanding on the topics.
- Before ending the course, promotion slides inclusive the benefits of joining IEEE EPS and upcoming IEMT conference were presented to the students. **Overall, the short course met the objective and was well received by the students judging from the online feedback given.**